



# 3D Packaging and Integration Japan TC Chapter

Japan Standards Spring Meetings 2025

Monday, May 19, 2025

Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

2:00 PM – 4:00 PM JST

## AGENDA

### 1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

### 2 Review of Previous Meeting Minutes

### 3 Liaison Report

- 3.1 JRSC Report
- 3.2 GCS Report
- 3.3 North America TC Chapter
- 3.4 Taiwan TC Chapter

### 4 Staff Report

### 5 Ballot Review

- 5.1 None

### 6 Subcommittee & Task Force Reports

- 6.1 3DS IC Bonded Layer Inspection Metrology Task Force
- 6.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force
- 6.3 3D Packaging & Integration 5-Year Review Task Force
- 6.4 3D Packaging & Integration Steering Group



## 7 Old Business

7.1 Project Period Review

7.2 5-Year Review

## 8 New Business

## 9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
3DP&I_20250203-01	SEMI Staff	To forward the result of ballot review for Doc.#7300 to the ISC A&R SC for procedural review.
3DP&I_20250203-02	SEMI Staff/ 5-Year Review TF	To check all the documents listed for 5-year review whether they are compliant with Style Manual.

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

## 10 Next Meeting and Adjournment